



NOTES:

1. ALL SENSOR FEATURES TO BE INTERPRETTED AS BEING REFERENCED TO THE U-V AXIS.
2. NECESSARY (REQUIRED) FEATURES AND DIMENSIONS ARE SHOWN WITHIN A BORDERED AREA WITH ADJACENT NOTATION; OTHER FEATURES MAY BE CHANGED SUBJECT TO SID PROJECT REVIEW.
3. SUGGESTED SENSING TRACE NUMBERING SCHEME: CONSISTS OF ARABIC NUMERALS EVERY TENTH SENSING TRACE WITH THE NUMERAL INDICATING THE TENTHS DIGIT. DOTS/SQUARES ARE USED TO INDICATE THE TENTHS DIGIT.
4. ALL TRACE LINES SHOWN INDICATE THE CENTER OF THE STRIPS.
5. UNPASSIVATED BOND/CONTACT/BOND PAD AREAS ARE DESCRIBED AND REQUIRED. CHANGES ARE SUBJECT TO SID PROJECT REVIEW.
6. THE SILICON CUT DIMENSIONS ARE FIXED AND REQUIRED.
7. THE EXPECTED ACTIVE LENGTH, ACTIVE AND CUT WIDTH AND DISTANCE FROM CUT END TO A.C. BOND PAD ARE BASED UPON HVV'S RECOMMENDATIONS. CHANGES ARE SUBJECT TO SID PROJECT REVIEW.
8. VENDOR IS RESPONSIBLE FOR DETERMINING GUARD RING AND BIAS RING STRUCTURE DESIGNS, ALBEIT SUBJECT TO SID PROJECT REVIEW.
9. FABRICATOR/DETAILS MAY BE CHANGED ALBEIT SUBJECT TO SID PROJECT REVIEW.

REV	DESCRIPTION	DATE	APPROVED	DATE
1		08-AUG-2008	T. NELSON	
2		05-SEP-2008	P. POLL	

UNLESS OTHERWISE SPECIFIED (ORIGINATOR) T. NELSON
 .XXX .XXX ANGLES DRAWN
 2 .001 E .001 ± 0.5 CHECKED
 7. BREAK ALL SHARP CORNERS APPROVED
 8. DO NOT SCALE DRAWING
 9. USE THE SURFACE FOR THE SURFACE
 4. SW. ALL BOND SERVICES USED ON
 MATERIAL AS NOTED
 5. DRAWING UNITS: METRIC

FERMILAB NATIONAL ACCELERATOR LABORATORY
 UNITED STATES DEPARTMENT OF ENERGY
 ILC EXPERIMENTS GENERAL
 SID SILICON DETECTOR
 U,V SILICON STRIP PARAMETERS

SCALE: 10:1 DRAWING NUMBER: 4901.000-ME-442189 SHEET 1 OF 1 REV
 CREATED WITH: Idec32MSys/ies [GROUP: PPD/MECHANICAL DEPARTMENT]